Progress about LGAD

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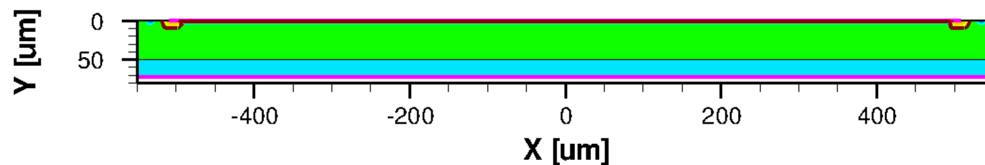
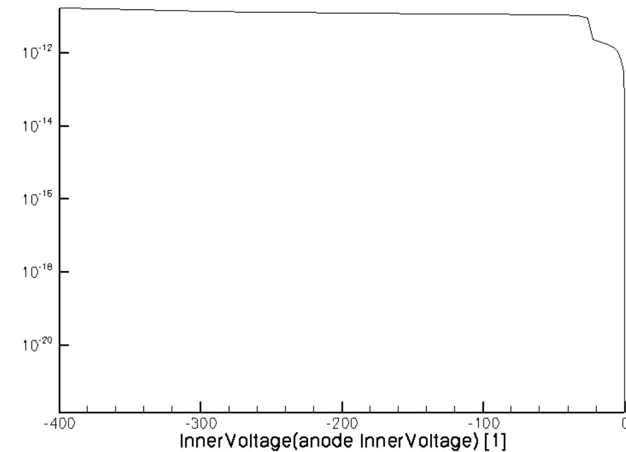
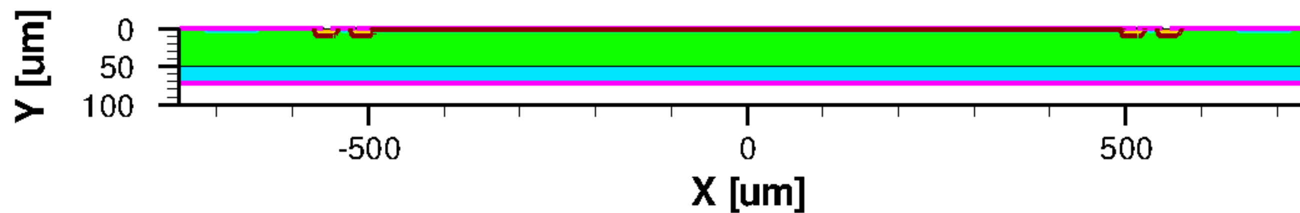
status

- Wafers are bought： 15k Ωcm bonding with CZ wafer (4 inch and 6 inch), 15k Ωcm FZ (4 inch and 6 inch), 10piece/type
- Low resistivity, 5k Ωcm and 15k Ωcm substrates will be used for the first tape-out, 4 inch wafer
- Foundry for the tape-out is ready now
- 2D model has been built and simulated, 3D is not completed.







Next

- More simulation will be done, including 2d, 3d, about I_V, Gain. Also will change the size and some doping density.
- Based on the simulation, some layout design will be carried out before 10.1 vacation.
- Concern more about the real technology. Carry out production process flow.

- **Discuss First tape-out:**

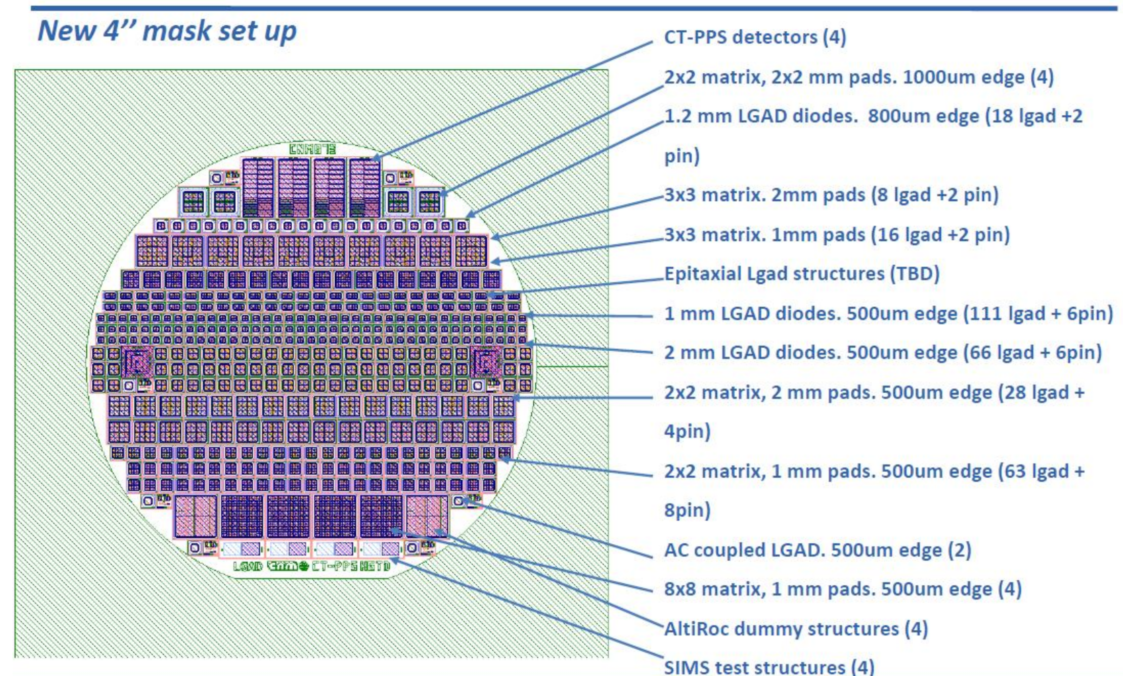
Shape： Square, Circle?

Size： 1mm, 2mm？

Array: 2×2, 5×5, 8×8？

With pad or not?

For testing？



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